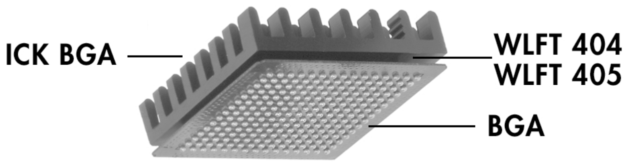
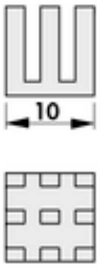
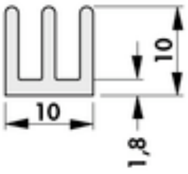
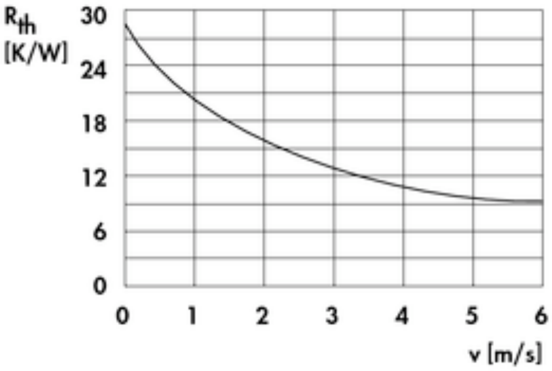
Heatsinks for BGAs / **ICK BGA 10 x 10 x 10**









10 x 10 x 10 mm, for IC design BGA and others

Parameters of article ICK BGA 10 x 10 x 10

R_{th} [K/W]	28.5
dissipation loss [W]	1.9
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	10
heigth [mm]	10
plate thickness [mm]	1.8
length on stock [mm]	10
surface treatment	black anodised

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 10 x 10**

Thermally conductive foil both sides adhesive / **WLFT 405 10 x 10**